



Product Change Notification

106615 - 00

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Product Change Notification

Change Notification #: 106615 - 00
Change Title: Intel® TXN31115D200000 4/2/1Gbps Small Form Factor Pluggable (SFP) Optical Transceivers, PCN 106615-00, Product Design
Date of Publication: July 28, 2006

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date of Samples Availability:	Jul 24, 2006
Date Customer Must be Ready to Receive Post-Conversion Material:	Oct 28, 2006
Date of First Availability of Post-Conversion Material:	Oct 28, 2006

The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.

Description of Change to the Customer:

1. SFP module mechanical changes

Intel has made the following changes to (a) improve product ESD performance, and (b) improved module retention, listed below:

(a) Changed bail material from metal to plastic to improve ESD performance

Requirement	Regulation	ESD Performance Level	
		Metal Bail	Plastic Bail (Production Release)
Electrostatic Discharge	EN-61000-4-2	+/- 8kV air discharge +/- 4kV contact discharge to face plate	+/- 15kV air discharge +/- 8kV contact discharge to face plate

Table 1 ESD Performance Improvement

(b) To improve module retention, the latch height has changed from 1.01 +/- 0.16mm +/- 0.16mm to 0.6 +/- 0.1mm

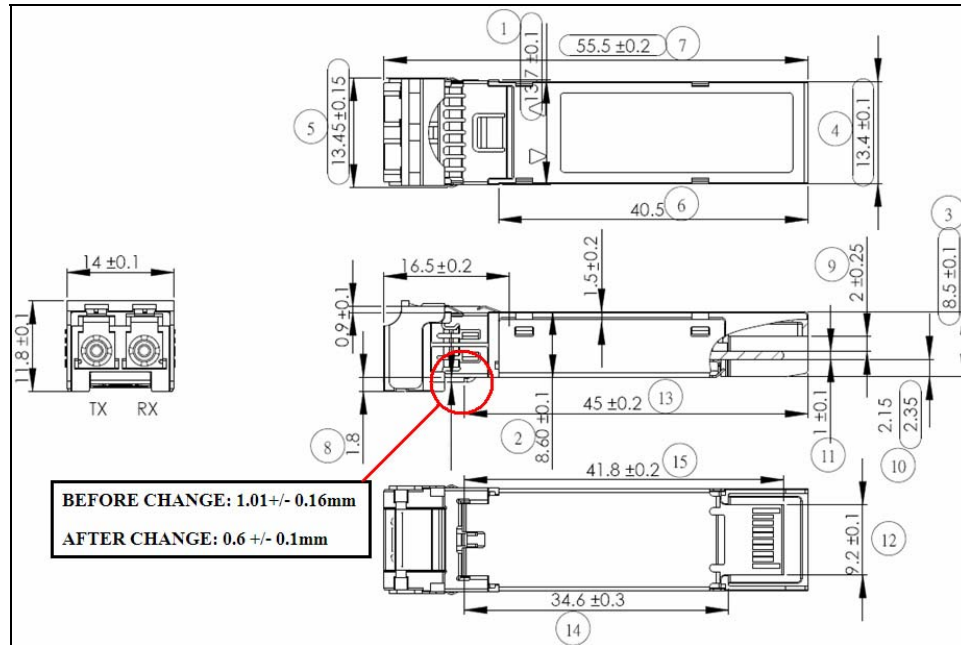


Figure 1 Latch Change

2. Firmware update to extend module initialization time

Change fuse setting from 0ms to 65ms start-up delay to enhance communication to I2C and overall stability of the microcontroller.

Customer Impact of Change and Recommended Action:

Samples have been made available on July 24, 2006 and customers may want to perform validation testing on mechanical changes and firmware update.

There will be no part number or MM number change.

Products Affected / Intel Ordering Codes:

System Products Table

Affected Product Code	Affected MM#
TXN31115D200000	874223

Reference Documents / Attachments:

Document:

1. TXN31115D200000 Product Change Summary.
PDF

Location #:

Contact local Intel FAE for document support

PCN Revision History:

Date of Revision:

July 28, 2006

Revision Number:

00

Reason:

Originally Published PCN